

CuSn6 HP

HP high performance

Standard Designation

EN CW452K / UNS 51900

Chemical Composition

Cu	Sn [%]	P [%]	
Balance	6	0.1	

Description / Applications

CuSn6 HP belongs to the copper-tin alloys. CuSn6 HP provides an extraordinary combination of strength and electrical conductivity. CuSn6 HP has elevated bending properties because of its fine-grained microstructure.

Applications: connectors, contact pins, springs, stamped pieces, parts in the machine and apparatus construction

Physical Properties¹⁾

Density	8.8 g/cm ³	Thermal expansion coefficient	18.5·10 ⁻⁶ /K
Electrical conductivity	9 m/Ω·mm ² 15 % IACS ²⁾	Modulus of elasticity	115 GPa ³⁾
Thermal conductivity	75 W/m·K		

¹⁾ Guideline values for soft temper, measured at room temperature

³⁾ 1 GPa = 1 kN/mm²
²⁾ IACS = International Annealed Copper Standard

Processing information

Weldability	good	Stress corrosion cracking	none
Solderability	very good		

Mechanical properties (maximum strip thickness 0.4 mm)

Temper	Tensile Strength Rm [MPa]	Yield Strength Rp0,2 [MPa]	Elongation A50 [%]	Hardness HV	Bendability ¹⁾			
					90° r/t ²⁾		180° r/t ²⁾	
					GW ³⁾	BW ⁴⁾	GW ³⁾	BW ⁴⁾
R550	550-650	min. 500	min. 16	170-220	0	0	0.5	1
R670	670-780	min. 660	min. 7	200-260	1	2	2	3.5

¹⁾ The r/t values are valid for a strip thickness up to 0.4 mm (without crack). The data refer to a width of the bending area of 5 mm.

V-shape bend test according to ISO 7438

²⁾ r = inner radius, t = thickness

³⁾ GW = good way

⁴⁾ BW = bad way

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